

| Ref # | Hits  | Search Query  | DBs             | Default Operator | Plurals | Time Stamp       |
|-------|-------|---|-----------------|------------------|---------|------------------|
| L15   | 54096 | (Cu or copper) and (stress\$6 or strain\$6 or compress\$6) and (solder\$6 or bump or ball)  | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:43 |
| L16   | 36495 | 15 and (adhesion or Ti or TiW or W or Cr or titanium or tungsten or chromium)   | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:43 |
| L17   | 12708 | 16 and (metallizat\$6 or pad or bondpad)  | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:43 |
| L18   | 10472 | 17 and (@ad<="20010921" or @rlad<="200140921")  | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:57 |
| L19   | 3658  | 18 and ((compress\$6 or squeez\$6 or compact or condens\$6 or reduc\$6) near5 (stress\$6 or strain\$6 or forc\$6))                | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 16:31 |
| L20   | 3507  | 19 and (substrate or wafer or semiconductor or base)  | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:55 |
| L21   | 9625  | 17 and (@ad<="20010921" or @rlad<="20010921")   | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:58 |
| L22   | 3150  | 20 and 21   | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:58 |
| L23   | 4148  | (Cu or copper) same (((compress\$6 or squeez\$6 or compact or condens\$6 or reduc\$6) near5 (stress\$6 or strain\$6 or forc\$6))) | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 16:32 |
| L24   | 444   | 22 and 23   | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 16:32 |

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|-------|-------|--|-----------------|------------------|---------|------------------|
| L15   | 54096 | (Cu or copper) and (stress\$6 or strain\$6 or compress\$6) and (solder\$6 or bump or ball)                         | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:43 |
| L16   | 36495 | 15 and (adhesion or Ti or TiW or W or Cr or titanium or tungsten or chromium)                                      | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:43 |
| L17   | 12708 | 16 and (metallizat\$6 or pad or bondpad)   | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:43 |
| L18   | 10472 | 17 and (@ad<="20010921" or @rlad<="200140921")   | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:57 |
| L19   | 3658  | 18 and ((compress\$6 or squeez\$6 or compact or condens\$6 or reduc\$6) near5 (stress\$6 or strain\$6 or forc\$6)) | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:48 |
| L20   | 3507  | 19 and (substrate or wafer or semiconductor or base)   | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:55 |
| L21   | 9625  | 17 and (@ad<="20010921" or @rlad<="20010921")  | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:58 |
| L22   | 3150  | 20 and 21  | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:58 |

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|-------|-------|--|-----------------|------------------|---------|------------------|
| L15   | 54096 | (Cu or copper) and (stress\$6 or strain\$6 or compress\$6) and (solder\$6 or bump or ball)                         | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:43 |
| L16   | 36495 | 15 and (adhesion or Ti or TiW or W or Cr or titanium or tungsten or chromium)                                      | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:43 |
| L17   | 12708 | 16 and (metallizat\$6 or pad or bondpad)   | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:43 |
| L18   | 10472 | 17 and (@ad<="20010921" or @rlad<="200140921")   | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:44 |
| L19   | 3658  | 18 and ((compress\$6 or squeez\$6 or compact or condens\$6 or reduc\$6) near5 (stress\$6 or strain\$6 or forc\$6)) | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:48 |
| L20   | 3507  | 19 and (substrate or wafer or semiconductor or base)   | US-PGPUB; USPAT | OR               | ON      | 2005/07/19 15:50 |

| Ref # | Hits  | Search Query  | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|-------|---|---|------------------|---------|------------------|
| L3    | 37953 | (Cu or copper) and (stress\$6 or strain\$6) and (solder\$6 or bump or ball)                   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/07/19 15:29 |
| L4    | 56440 | (Cu or copper) and (stress\$6 or strain\$6 or compress\$6) and (solder\$6 or bump or ball)    | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/07/19 15:30 |
| L5    | 11838 | ((Cu or copper) same (stress\$6 or strain\$6 or compress\$6)) and (solder\$6 or bump or ball) | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/07/19 15:30 |
| L6    | 7478  | 5 and (adhesion or Ti or TiW or W or Cr or titanium or tungsten or chromium)                  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/07/19 15:32 |
| L8    | 55    | 6 and (metallizat\$6 or pad or bondpad)   | EPO; JPO;<br>DERWENT;<br>IBM_TDB                        | OR               | ON      | 2005/07/19 15:33 |